Wire Wound Chip Inductor
-YWLD1608T Series

■ Features

- Minature size,suitable for SMT.
- Using terminal electrode structure to restrain the parasitic component effect quite caused by lead.
- Execellent in solderability and heat resistance.
- Best frequency special property and intense ability to resist interference.
- Operating temperature:-40℃ ~ +85℃.

■ Applications

- Protable communication equipment and PDA,high speed electronic device.
- Used for radiation high speed noise suppression.

■ Product Identification

YWLD □□□□□ - □□□ - □

(1) (2) (3) (4)

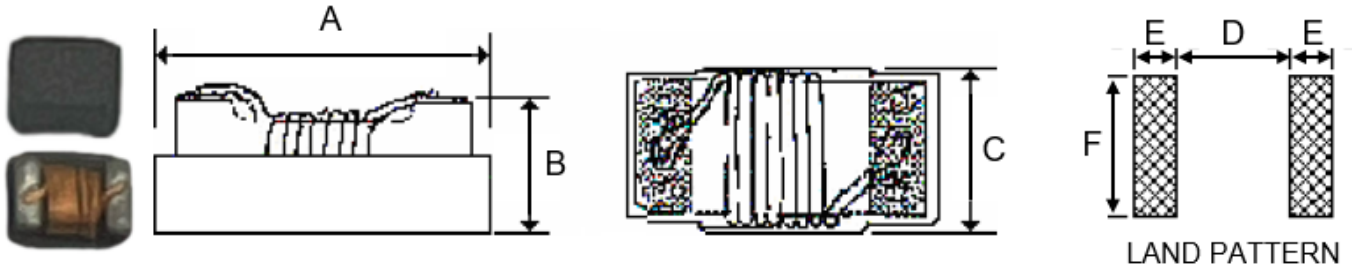
(1)： Type

(2)： Dimensions

(3)： Inductance value

(4)： Inductance Tolerance: M=±20%,K=±10%,J=±5%

■ Shapes and Dimensions (Unit：mm)



TYPE	A Max.	B Max.	C Max.	D Typ.	E Typ.	F Typ.
YWLD1608T	1.80	1.10	1.25	0.64	0.64	1.02

■ YWLD1608T Series

Part Number	L (uH)	Freq. (MHz)	Q Typ.	SRF Typ. (MHz)	Rdc±30% (Ω)	Isat Typ. (mA)	Irms Typ. (mA)
YWLD1608T-1R0M	1.0±20%	1	10	350	0.14	800	900
YWLD1608T-2R2M	2.2±20%	1	10	90	0.30	580	600
YWLD1608T-4R7M	4.7±20%	1	10	57	0.46	450	500
YWLD1608T-6R8M	6.8±20%	1	9	25	0.67	410	500
YWLD1608T-100M	10±20%	1	9	25	1.00	270	380
YWLD1608T-150M	15±20%	1	9	25	1.42	220	350
YWLD1608T-220M	22±20%	1	8	20	2.46	180	270

※ Rating DC current:temperature rise(ΔT) is 40 ℃ approximately at Irms.

※ Saturation DC current:Inductance drop approximately 30% of L0 at Isat.

※ Storage temp.:-10℃ ~ + 40℃ R.H.:65% Max.

※ Moisture sensitivity level(MSL)2(1 year floor life at<30℃/65% relative humidity)

■ Soldering Conditions

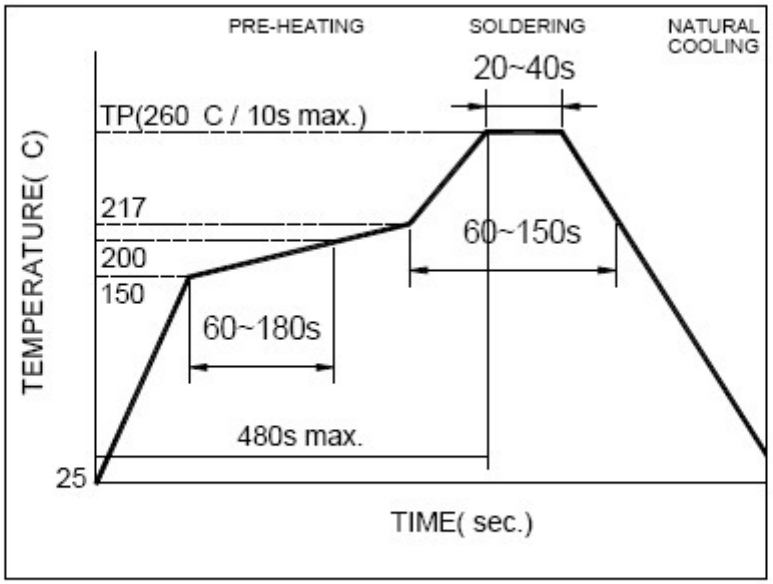


Figure 1. Re-flow Soldering (Lead Free)

Note:
- Preheat circuit and products to 150℃
- 260℃ tip temperature (max)
- Reflow times: no more than 2 times
- Solder paste thickness: the best 0.08mm is ,but max is 0.1mm

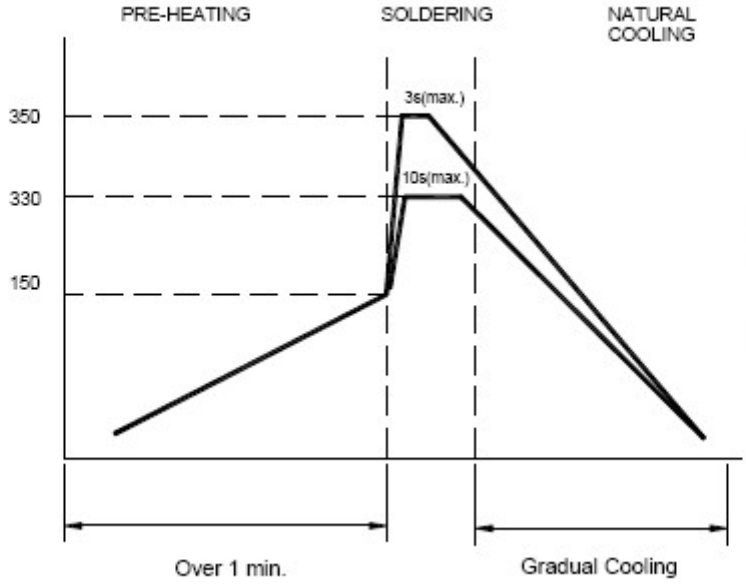
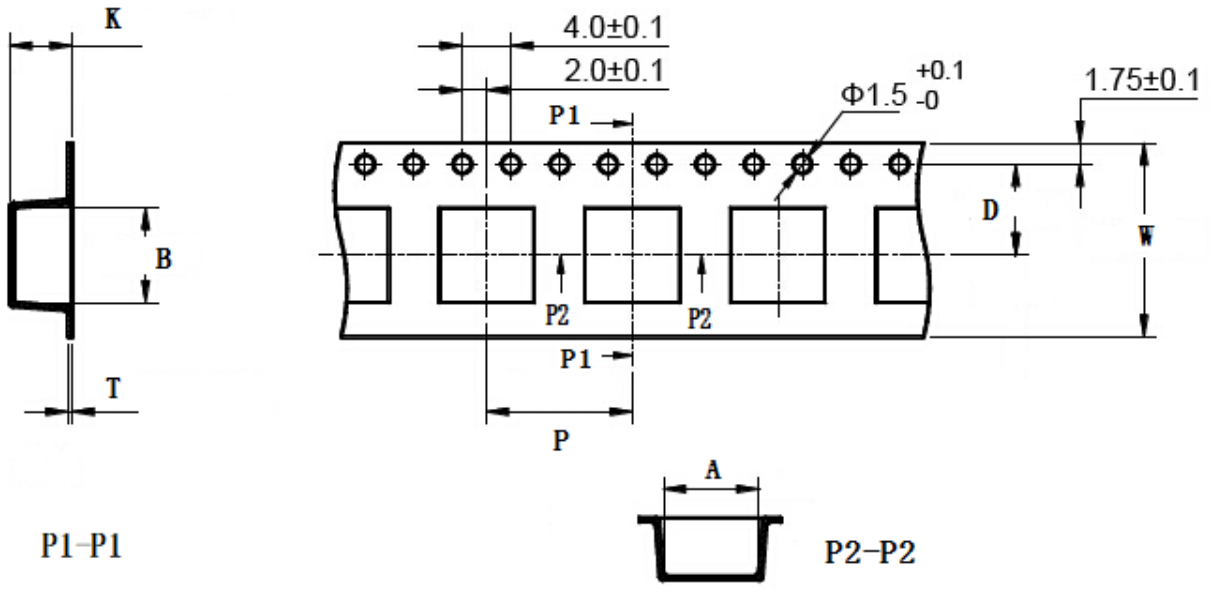


Figure 2. Hand Soldering

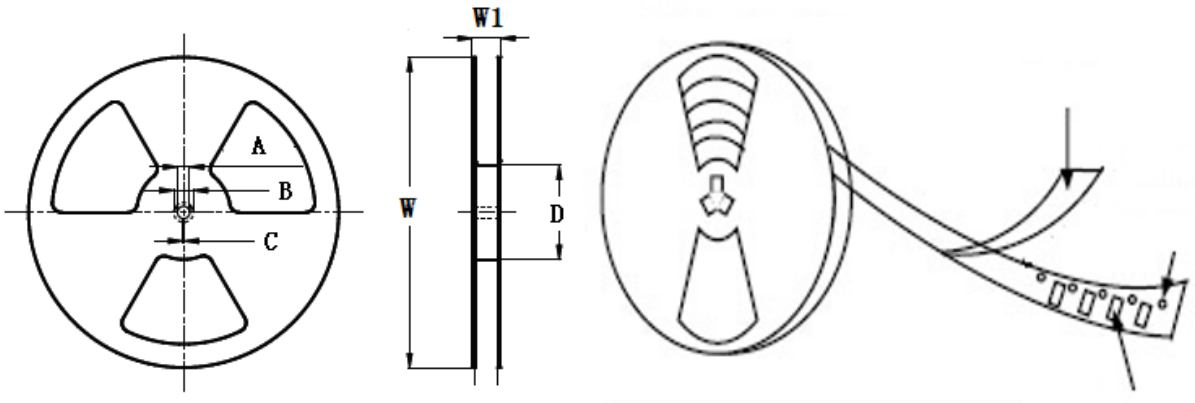
Note:
- Use a 20 watt soldering iron with tip diameter of 1.0mm
- Limit soldering time to 3 sec.

■ Taping Dimensions(Unit:mm)



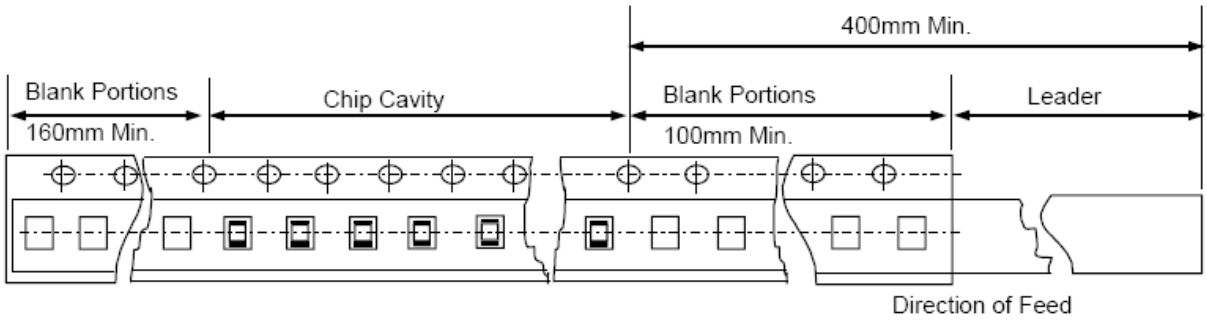
TYPE	W	A	B	D	P	K	T	MPQ
YWLD1608T	8.0±0.1	1.0±0.2	1.8±0.2	3.5±0.1	4.0±0.1	0.95+0.1	0.22±0.05	4000

■ Reel Dimensions(Unit:mm)



TYPE	W	W1	A	B	C	D
YWLD1608T	178±2.0	8.40±1.50	4.3±0.20	5.0±0.10	3.0±0.10	58±2.0

■ Leader and Blank portion



1．Missing chips number within 0.1% of the number per reel or 1pcs, whichever is greater, and are not continuous.

2．The top tape and bottom tape shall not protrude beyond the edges of the tape and shall not cover sprocket hole.

3．Cumulative tolerance of sprocket holes, 10 pitches: ±0.3mm.

4．Peeling off force: 10gf to 100gf in the direction show below for 8mm carrier tapes and 10gf to 130gf for 12mm to 56mm wide carrier tapes.

